Microsemi Corporation - AX2000-1FGG1152I Datasheet

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Discontinued at Digi-Key
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	684
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	1152-BGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax2000-1fgg1152i

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2 – Detailed Specifications

Operating Conditions

Table 2-1 lists the absolute maximum ratings of Axcelerator devices. Stresses beyond the ratings may cause permanent damage to the device. Exposure to Absolute Maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the recommendations in Table 2-2.

***Table 2-1* • Absolute Maximum Ratings**

Symbol	Parameter	Limits	Units
VCCA	DC Core Supply Voltage	–0.3 to 1.7	V
VCCI	DC I/O Supply Voltage	–0.3 to 3.75	V
VREF	DC I/O Reference Voltage	–0.3 to 3.75	V
VI	Input Voltage	–0.5 to 4.1	V
VO	Output Voltage	–0.5 to 3.75	V
TSTG	Storage Temperature	–60 to +150	°C
VCCDA*	Supply Voltage for Differential I/Os	–0.3 to 3.75	V

*Note: * Should be the maximum of all VCCI.*

***Table 2-2* • Recommended Operating Conditions**

Parameter Range	Commercial	Industrial	Military	Units
Ambient Temperature (T_A)[1]	0 to +70	–40 to +85	–55 to +125	°C
1.5 V Core Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.5 V I/O Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.8 V I/O Supply Voltage	1.71 to 1.89	1.71 to 1.89	1.71 to 1.89	V
2.5 V I/O Supply Voltage	2.375 to 2.625	2.375 to 2.625	2.375 to 2.625	V
3.3 V I/O Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VCCDA Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VPUMP Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V

Notes:

1. *Ambient temperature (T_A) is used for commercial and industrial grades; case temperature (T_C) is used for military grades.*
2. *T_J max = 125°C*

Power-Up/Down Sequence

All Axcelerator I/Os are tristated during power-up until normal device operating conditions are reached, when I/Os enter user mode. VCCDA should be powered up before (or coincidentally with) VCCA and VCCI to ensure the behavior of user I/Os at system start-up. Conversely, VCCDA should be powered down after (or coincidentally with) VCCA and VCCI. Note that VCCI and VCCA can be powered up in any sequence with respect to each other, provided the requirement with respect to VCCDA is satisfied.

Table 2-5 • Different Components Contributing to the Total Power Consumption in Axcelerator Devices

Component	Definition	Device Specific Value (in µW/MHz)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

Ptotal = Pdc + Pac

P_{dc} = ICCA * VCCA

P_{ac} = $P_{HCLK} + P_{CLK} + P_{R\text{-cells}} + P_{C\text{-cells}} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$

P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PCLK = (P4 + P5 * s + P6 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PR-cells = P7 * ms * Fs

ms = the number of R-cells switching at each Fs cycle

Fs = the clock frequency

PC-cells = P8 * mc * Fs

mc = the number of C-cells switching at each Fs cycle

Fs = the clock frequency

Pinputs = P9 * pi * Fpi

pi = the number of inputs

F_{pi} = the average input frequency

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors**
(Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)

VCCA	Junction Temperature						
	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

I/O Clusters

Each I/O cluster incorporates two I/O modules, four RX modules, two TX modules, and a buffer module. In turn, each I/O module contains one Input Register (InReg), one Output Register (OutReg), and one Enable Register (EnReg) (Figure 2-5).

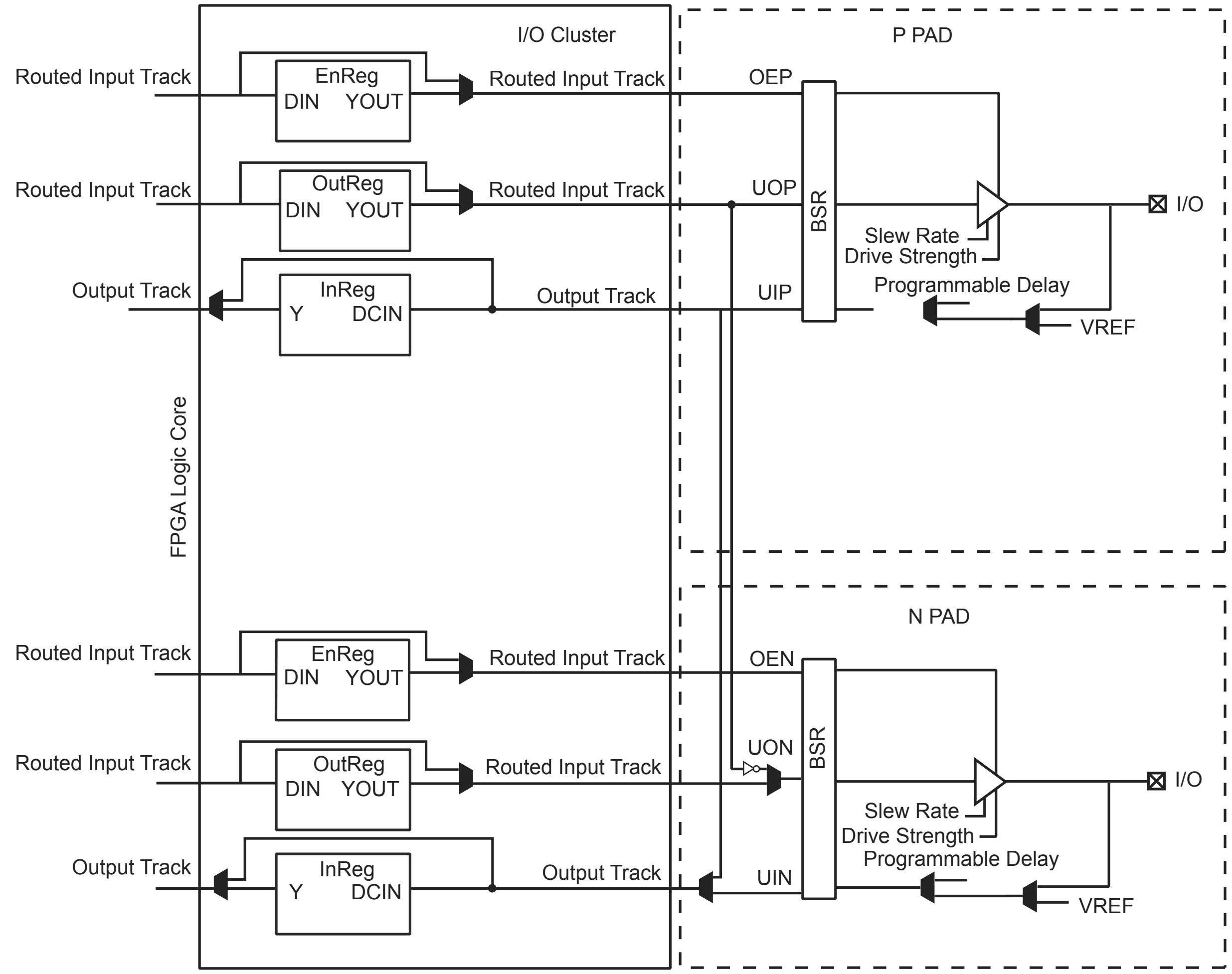

Figure 2-5 • **I/O Cluster Interface**

Using an I/O Register

To access the I/O registers, registers must be instantiated in the netlist and then connected to the I/Os. Usage of each I/O register (register combining) is individually controlled and can be selected/deselected using the PinEditor tool in the Designer software. I/O register combining can also be controlled at the device level, affecting all I/Os. Please note, the I/O register option is deselected by default in any given design.[4]

In addition, Designer software provides a global option to enable/disable the usage of registers in the I/Os. This option is design-specific. The setting for each individual I/O overrides this global option. Furthermore, the *global set fuse* option in the Designer software, when checked, causes all I/O registers to output logic High at device power-up.

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[4] *Please note that register combining for multi fanout nets is not supported.*

Table 2-22 **• 3.3 V LVTTL I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)**

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 1 (8 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		4.23		4.81		5.66	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		4.64		5.28		6.21	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.23		4.81		5.66	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.89		1.91		1.91	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.01		2.02		2.03	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

Table 2-28 • **1.8V LVCMOS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.7 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS18 Output Module Timing								
t_{DP}	Input Buffer		3.26		3.71		4.37	ns
t_{PY}	Output Buffer		4.55		5.18		6.09	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.82		2.83		2.84	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.43		3.45		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.01		6.85		8.05	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.73		7.67		9.01	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Module Specifications

C-Cell

Introduction

The C-cell is one of the two logic module types in the AX architecture. It is the combinatorial logic resource in the Axcelerator device. The AX architecture implements a new combinatorial cell that is an extension of the C-cell implemented in the SX-A family. The main enhancement of the new C-cell is the addition of carry-chain logic.

The C-cell can be used in a carry-chain mode to construct arithmetic functions. If carry-chain logic is not required, it can be disabled.

The C-cell features the following (Figure 2-27):

- Eight-input MUX (data: D0-D3, select: A0, A1, B0, B1). User signals can be routed to any one of these inputs. Any of the C-cell inputs (D0-D3, A0, A1, B0, B1) can be tied to one of the four routed clocks (CLKE/F/G/H).
- Inverter (DB input) can be used to drive a complement signal of any of the inputs to the C-cell.
- A carry input and a carry output. The carry input signal of the C-cell is the carry output from the C-cell directly to the north.
- Carry connect for carry-chain logic with a signal propagation time of less than 0.1 ns.
- A hardwired connection (direct connect) to the adjacent R-cell (Register Cell) for all C-cells on the east side of a SuperCluster with a signal propagation time of less than 0.1 ns.

This layout of the C-cell (and the C-cell Cluster) enables the implementation of over 4,000 functions of up to five bits. For example, two C-cells can be used together to implement a four-input XOR function in a single cell delay.

The carry-chain configuration is handled automatically for the user with Microsemi's extensive macro library (please see the *Antifuse Macro Library Guide* for a complete listing of available Axcelerator macros).

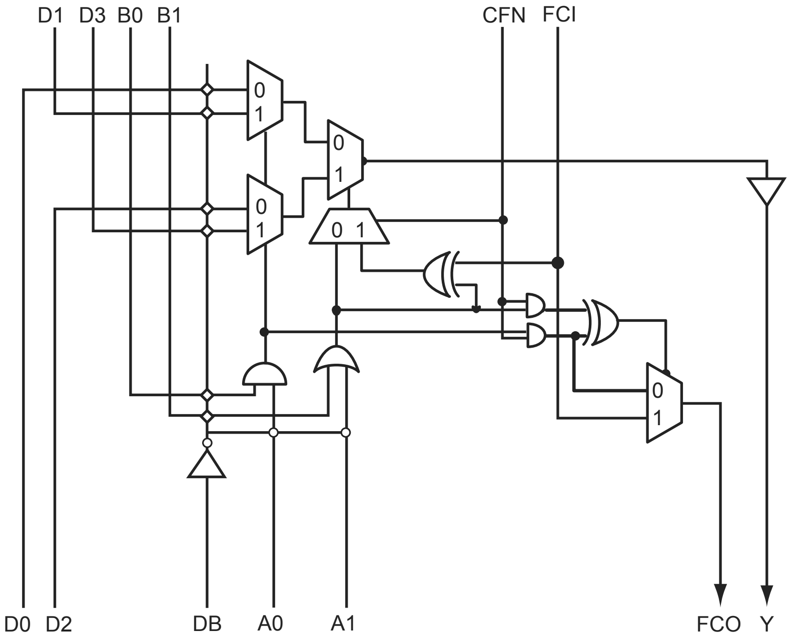

Figure 2-27 • **C-Cell**

Routing Specifications

Routing Resources

The routing structure found in Axcelerator devices enables any logic module to be connected to any other logic module while retaining high performance. There are multiple paths and routing resources that can be used to route one logic module to another, both within a SuperCluster and elsewhere on the chip.

There are four primary types of routing within the AX architecture: DirectConnect, CarryConnect, FastConnect, and Vertical and Horizontal Routing.

DirectConnect

DirectConnects provide a high-speed connection between an R-cell and its adjacent C-cell (Figure 2-35). This connection can be made from DCOUT of the C-cell to DCIN of the R-cell by configuring of the S1 line of the R-cell. This provides a connection that does not require an antifuse and has a delay of less than 0.1 ns.

***Figure 2-35* • DirectConnect and CarryConnect**

CarryConnect

CarryConnects are used to build carry chains for arithmetic functions (Figure 2-35). The FCO output of the right C-cell of a two-C-cell Cluster drives the FCI input of the left C-cell in the two-C-cell Cluster immediately below it. This pattern continues down both sides of each SuperCluster column.

Similar to the DirectConnects, CarryConnects can be built without an antifuse connection. This connection has a delay of less than 0.1 ns from the FCO of one two-C-cell cluster to the FCI of the two-C-cell cluster immediately below it (see the "Carry-Chain Logic" section on page 2-56 for more information).

FastConnect

For high-speed routing of logic signals, FastConnects can be used to build a short distance connection using a single antifuse (Figure 2-36 on page 2-62). FastConnects provide a maximum delay of 0.3 ns. The outputs of each logic module connect directly to the Output Tracks within a SuperCluster. Signals on the Output Tracks can then be routed through a single antifuse connection to drive the inputs of logic modules either within one SuperCluster or in the SuperCluster immediately below it.

Implementation Example:

Figure 2-47 shows a complex clock distribution example. The reference clock (RefCLK) of PLLE is being sourced from non-clock signal pins (INBUF to PLLINT). The CLK1 output of PLLE is being fed to the RefCLK input of PLLF. The CLK2 output of PLLE is driving logic (via PLLOUT). In turn, this logic is driving the global resource CLKE. PLLF is driving both CLKF and CLKG global resources.

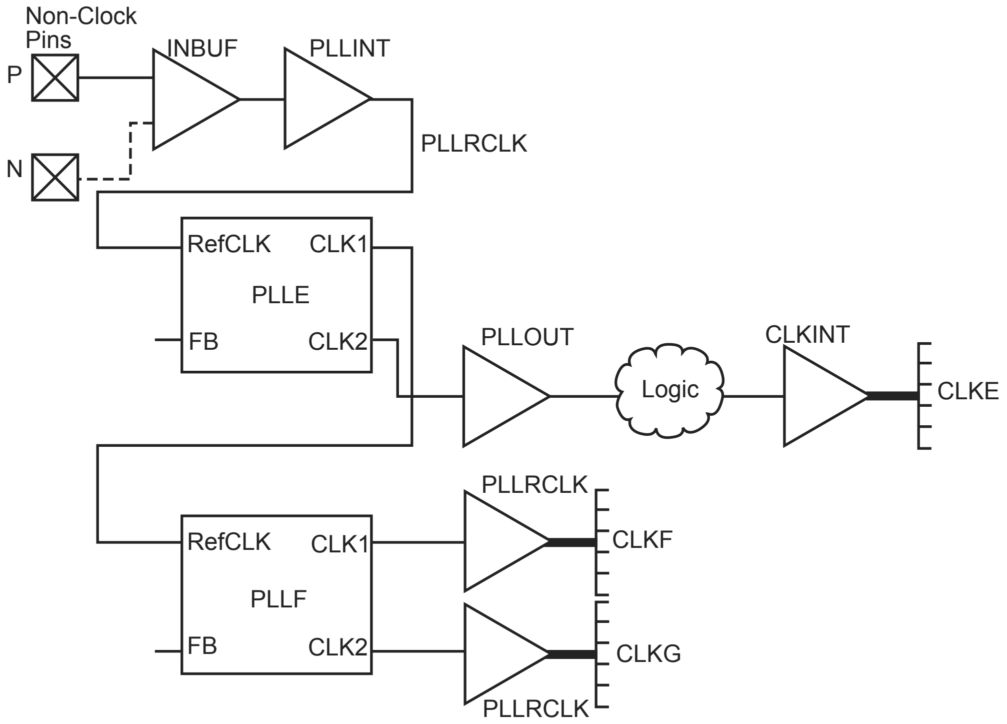

Figure 2-47 • **Complex Clock Distribution Example**

Table 2-101 • **Eight FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		15.46		17.61		20.70	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		5.13		5.13		5.13	ns
t_{WCKP}	Minimum WCLK Period	5.88		5.88		5.88		ns
t_{RSU}	Read Setup		16.22		18.47		21.72	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		5.77		5.77		5.77	ns
t_{RCKP}	Minimum RCLK period	6.50		6.50		6.50		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		3.39		3.86		4.54	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		4.93		5.62		6.61	ns

Note: Timing data for these eight cascaded FIFO blocks uses a depth of 32,768. For all other combinations, use Microsemi's timing software.

FG676	
AX500 Function	**Pin Number**
IO51NB2F4	L20
IO51PB2F4	L21
IO52NB2F5	K26
IO52PB2F5	J26
IO53NB2F5	L23
IO53PB2F5	L22
IO54NB2F5	L24
IO54PB2F5	K24
IO55NB2F5	M20
IO55PB2F5	M21
IO56NB2F5	L26
IO56PB2F5	L25
IO57NB2F5	M23
IO57PB2F5	M22
IO58NB2F5	M26
IO58PB2F5	M25
IO59NB2F5	N22
IO59PB2F5	N23
IO60NB2F5	N24
IO60PB2F5	M24
IO61NB2F5	N20
IO61PB2F5	N21
IO62NB2F5	P25
IO62PB2F5	N25
Bank 3	
IO63NB3F6	T26
IO63PB3F6	R26
IO64NB3F6	R24
IO64PB3F6	P24
IO65NB3F6	P20
IO65PB3F6	P21
IO66NB3F6	T25
IO66PB3F6	R25
IO67NB3F6	T23
IO67PB3F6	R23

FG676	
AX500 Function	**Pin Number**
IO68NB3F6	V26
IO68PB3F6	U26
IO69NB3F6	V25
IO69PB3F6	U25
IO70NB3F6	Y25
IO70PB3F6	W25
IO71NB3F6	W24
IO71PB3F6	V24
IO72NB3F6	V23
IO72PB3F6	U23
IO73NB3F6	T21
IO73PB3F6	T20
IO74NB3F7	AA26
IO74PB3F7	Y26
IO75NB3F7	AA24
IO75PB3F7	Y24
IO76NB3F7	Y23
IO76PB3F7	W23
IO77NB3F7	V21
IO77PB3F7	U21
IO78NB3F7	AB25
IO78PB3F7	AA25
IO79NB3F7	AC26
IO79PB3F7	AB26
IO80NB3F7	AC24
IO80PB3F7	AB24
IO81NB3F7	AB23
IO81PB3F7	AA23
IO82NB3F7	AA22
IO82PB3F7	Y22
IO83NB3F7	AE26
IO83PB3F7	AD26
Bank 4	
IO84NB4F8	AB21
IO84PB4F8	AA21

FG676	
AX500 Function	**Pin Number**
IO85NB4F8	AE23
IO85PB4F8	AE24
IO86NB4F8	AC21
IO86PB4F8	AC22
IO87NB4F8	AF22
IO87PB4F8	AF23
IO88NB4F8	AD22
IO88PB4F8	AD23
IO89NB4F8	AC19
IO89PB4F8	AC20
IO90NB4F8	AE21
IO90PB4F8	AE22
IO91NB4F8	AA17
IO91PB4F8	AA18
IO92NB4F8	AD20
IO92PB4F8	AD21
IO93NB4F8	AF20
IO93PB4F8	AF21
IO94NB4F9	AE19
IO94PB4F9	AE20
IO95NB4F9	AC17
IO95PB4F9	AC18
IO96NB4F9	AD18
IO96PB4F9	AD19
IO97NB4F9	AA16
IO97PB4F9	Y16
IO98NB4F9	AE17
IO98PB4F9	AE18
IO99NB4F9	AC16
IO99PB4F9	AB16
IO100NB4F9	AF17
IO100PB4F9	AF18
IO101NB4F9	AA15
IO101PB4F9	Y15
IO102NB4F9	AC15

FG676	
AX500 Function	**Pin Number**
IO102PB4F9	AB15
IO103NB4F9/CLKEN	AE16
IO103PB4F9/CLKEP	AF16
IO104NB4F9/CLKFN	AE14
IO104PB4F9/CLKFP	AE15
Bank 5	
IO105NB5F10/CLKGN	AE12
IO105PB5F10/CLKGP	AE13
IO106NB5F10/CLKHN	AE11
IO106PB5F10/CLKHP	AF11
IO107NB5F10	Y12
IO107PB5F10	AA13
IO108NB5F10	AC12
IO108PB5F10	AB12
IO109NB5F10	AC10
IO109PB5F10	AC11
IO110NB5F10	AF9
IO110PB5F10	AF10
IO111NB5F10	Y11
IO111PB5F10	AA12
IO112NB5F10	AE9
IO112PB5F10	AE10
IO113NB5F10	AC9
IO113PB5F10	AD9
IO114NB5F11	AF6
IO114PB5F11	AF7
IO115NB5F11	AA10
IO115PB5F11	AB10
IO116NB5F11	AE7
IO116PB5F11	AE8
IO117NB5F11	AD7
IO117PB5F11	AD8
IO118NB5F11	AC7
IO118PB5F11	AC8
IO119NB5F11	AD6

FG676	
AX500 Function	**Pin Number**
IO119PB5F11	AE6
IO120NB5F11	AE5
IO120PB5F11	AF5
IO121NB5F11	AF4
IO121PB5F11	AE4
IO122NB5F11	AC5
IO122PB5F11	AC6
IO123NB5F11	AD4
IO123PB5F11	AD5
IO124NB5F11	AB6
IO124PB5F11	AB7
IO125NB5F11	AE3
IO125PB5F11	AF3
Bank 6	
IO126NB6F12	AB3
IO126PB6F12	AC3
IO127NB6F12	AA2
IO127PB6F12	AB2
IO128NB6F12	AC2
IO128PB6F12	AD2
IO129NB6F12	Y1
IO129PB6F12	AA1
IO130NB6F12	Y3
IO130PB6F12	AA3
IO131NB6F12	U6
IO131PB6F12	V6
IO132NB6F12	W2
IO132PB6F12	Y2
IO133NB6F12	V4
IO133PB6F12	W4
IO134NB6F12	V3
IO134PB6F12	W3
IO135NB6F12	V1
IO135PB6F12	V2
IO136NB6F13	U4

FG676	
AX500 Function	**Pin Number**
IO136PB6F13	U5
IO137NB6F13	T6
IO137PB6F13	T7
IO138NB6F13	T5
IO138PB6F13	T4
IO139NB6F13	R6
IO139PB6F13	R7
IO140NB6F13	T3
IO140PB6F13	U3
IO141NB6F13	U1
IO141PB6F13	U2
IO142NB6F13	R2
IO142PB6F13	T2
IO143NB6F13	P3
IO143PB6F13	R3
IO144NB6F13	P5
IO144PB6F13	P4
IO145NB6F13	P6
IO145PB6F13	P7
IO146NB6F13	R1
IO146PB6F13	T1
Bank 7	
IO147NB7F14	N6
IO147PB7F14	N7
IO148NB7F14	N5
IO148PB7F14	N4
IO149NB7F14	N2
IO149PB7F14	N3
IO150NB7F14	L1
IO150PB7F14	M1
IO151NB7F14	M2
IO151PB7F14	M3
IO152NB7F14	M5
IO152PB7F14	M4
IO153NB7F14	M7

FG896	
AX1000 Function	**Pin Number**
IO155NB4F14	AC17
IO155PB4F14	AB17
IO156NB4F14	AK19
IO156PB4F14	AJ19
IO157NB4F14	AE17
IO157PB4F14	AD17
IO158NB4F14	AJ17
IO158PB4F14	AJ18
IO159NB4F14/CLKEN	AG18
IO159PB4F14/CLKEP	AH18
IO160NB4F14/CLKFN	AG16
IO160PB4F14/CLKFP	AG17
Bank 5	
IO161NB5F15/CLKGN	AG14
IO161PB5F15/CLKGP	AG15
IO162NB5F15/CLKHN	AG13
IO162PB5F15/CLKHP	AH13
IO163NB5F15	AE14
IO163PB5F15	AD14
IO164NB5F15	AJ12
IO164PB5F15	AJ13
IO165NB5F15	AB14
IO165PB5F15	AC15
IO166NB5F15	AK11
IO166PB5F15	AK12
IO167NB5F15	AB13
IO167PB5F15	AC14
IO168NB5F15	AH11
IO168PB5F15	AH12
IO169NB5F15	AD13
IO169PB5F15	AC13
IO170NB5F15	AJ10
IO170PB5F15	AJ11
IO171NB5F16	AG11
IO171PB5F16	AG12

FG896	
AX1000 Function	**Pin Number**
IO172NB5F16	AK9
IO172PB5F16	AK10
IO173NB5F16	AE12
IO173PB5F16	AE13
IO174NB5F16	AG9
IO174PB5F16	AG10
IO175NB5F16	AE11
IO175PB5F16	AF11
IO176NB5F16	AH8
IO176PB5F16	AH9
IO177NB5F16	AC12
IO177PB5F16	AD12
IO178NB5F16	AJ7
IO178PB5F16	AJ8
IO179NB5F16	AF9
IO179PB5F16	AF10
IO180NB5F16	AE9
IO180PB5F16	AE10
IO181NB5F17	AC11
IO181PB5F17	AD11
IO182NB5F17	AK6
IO182PB5F17	AK7
IO183NB5F17	AF8
IO183PB5F17	AG8
IO184NB5F17	AG7
IO184PB5F17	AH7
IO185NB5F17	AC10
IO185PB5F17	AD10
IO186NB5F17	AJ5
IO186PB5F17	AJ6
IO187NB5F17	AE7
IO187PB5F17	AE8
IO188NB5F17	AF6
IO188PB5F17	AF7
IO189NB5F17	AD8

FG896	
AX1000 Function	**Pin Number**
IO189PB5F17	AD9
IO190NB5F17	AH6
IO190PB5F17	AG6
IO191NB5F17	AG5
IO191PB5F17	AH5
IO192NB5F17	AC8
IO192PB5F17	AC9
Bank 6	
IO193NB6F18	AB7
IO193PB6F18	AC7
IO194NB6F18	AD5
IO194PB6F18	AE5
IO195NB6F18	AB6
IO195PB6F18	AC6
IO196NB6F18	AE4
IO196PB6F18	AF4
IO197NB6F18	AA8
IO197PB6F18	AB8
IO198NB6F18	AF3
IO198PB6F18	AG3
IO199NB6F18	AC4
IO199PB6F18	AD4
IO200NB6F18	AB5
IO200PB6F18	AC5
IO201NB6F18	Y7
IO201PB6F18	AA7
IO202NB6F18	AD3
IO202PB6F18	AE3
IO203NB6F19	Y6
IO203PB6F19	AA6
IO204NB6F19	Y5
IO204PB6F19	AA5
IO205NB6F19	W8
IO205PB6F19	Y8
IO206NB6F19	AA4

CQ208	
AX250 Function	**Pin Number**
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ352	
AX250 Function	**Pin Number**
IO64PB4F4	167
IO65NB4F4	170
IO65PB4F4	171
IO66NB4F4	164
IO66PB4F4	165
IO67NB4F4	160
IO67PB4F4	161
IO68NB4F4	158
IO68PB4F4	159
IO70NB4F4	154
IO70PB4F4	155
IO72NB4F4	152
IO72PB4F4	153
IO73NB4F4	146
IO73PB4F4	147
IO74NB4F4/CLKEN	142
IO74PB4F4/CLKEP	143
IO75NB4F4/CLKFN	136
IO75PB4F4/CLKFP	137
Bank 5	
IO76NB5F5/CLKGN	128
IO76PB5F5/CLKGP	129
IO77NB5F5/CLKHN	122
IO77PB5F5/CLKHP	123
IO78NB5F5	112
IO78PB5F5	113
IO79NB5F5	118
IO79PB5F5	119
IO80NB5F5	110
IO80PB5F5	111
IO82NB5F5	106
IO82PB5F5	107
IO84NB5F5	100
IO84PB5F5	101
IO85NB5F5	104

CQ352	
AX250 Function	**Pin Number**
IO85PB5F5	105
IO86NB5F5	98
IO86PB5F5	99
IO87NB5F5	94
IO87PB5F5	95
IO89NB5F5	92
IO89PB5F5	93
Bank 6	
IO90PB6F6	86
IO91NB6F6	84
IO91PB6F6	85
IO92NB6F6	78
IO92PB6F6	79
IO93NB6F6	82
IO93PB6F6	83
IO95NB6F6	76
IO95PB6F6	77
IO96NB6F6	72
IO96PB6F6	73
IO97NB6F6	70
IO97PB6F6	71
IO98NB6F6	66
IO98PB6F6	67
IO99NB6F6	64
IO99PB6F6	65
IO100NB6F6	60
IO100PB6F6	61
IO101NB6F6	58
IO101PB6F6	59
IO103NB6F6	54
IO103PB6F6	55
IO104NB6F6	52
IO104PB6F6	53
IO105NB6F6	48
IO105PB6F6	49

CQ352	
AX250 Function	**Pin Number**
IO106NB6F6	46
IO106PB6F6	47
Bank 7	
IO107NB7F7	40
IO107PB7F7	41
IO108NB7F7	42
IO108PB7F7	43
IO109NB7F7	36
IO109PB7F7	37
IO110NB7F7	34
IO110PB7F7	35
IO111NB7F7	30
IO111PB7F7	31
IO113NB7F7	28
IO113PB7F7	29
IO114NB7F7	24
IO114PB7F7	25
IO115NB7F7	22
IO115PB7F7	23
IO116NB7F7	18
IO116PB7F7	19
IO117NB7F7	16
IO117PB7F7	17
IO118NB7F7	12
IO118PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121NB7F7	6
IO121PB7F7	7
IO123NB7F7	4
IO123PB7F7	5
Dedicated I/O	
GND	1
GND	9
GND	15

CQ352	
AX250 Function	**Pin Number**
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX250 Function	**Pin Number**
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CQ352		CQ352		CQ352	
AX1000 Function	**Pin Number**	**AX1000 Function**	**Pin Number**	**AX1000 Function**	**Pin Number**
GND	21	GND	240	VCCA	14
GND	27	GND	246	VCCA	32
GND	33	GND	252	VCCA	56
GND	39	GND	258	VCCA	74
GND	45	GND	264	VCCA	87
GND	51	GND	265	VCCA	102
GND	57	GND	274	VCCA	114
GND	63	GND	280	VCCA	150
GND	69	GND	286	VCCA	162
GND	75	GND	292	VCCA	175
GND	81	GND	298	VCCA	191
GND	88	GND	310	VCCA	209
GND	89	GND	322	VCCA	233
GND	97	GND	330	VCCA	251
GND	103	GND	334	VCCA	263
GND	109	GND	340	VCCA	279
GND	115	GND	345	VCCA	291
GND	121	GND	352	VCCA	329
GND	133	NC	91	VCCA	339
GND	145	NC	130	VCCDA	2
GND	151	NC	131	VCCDA	44
GND	157	NC	174	VCCDA	90
GND	163	NC	268	VCCDA	116
GND	169	NC	307	VCCDA	117
GND	176	NC	308	VCCDA	132
GND	177	PRA	312	VCCDA	148
GND	186	PRB	311	VCCDA	149
GND	192	PRC	135	VCCDA	178
GND	198	PRD	134	VCCDA	221
GND	204	TCK	349	VCCDA	266
GND	210	TDI	348	VCCDA	293
GND	216	TDO	347	VCCDA	294
GND	222	TMS	350	VCCDA	309
GND	228	TRST	351	VCCDA	327
GND	234	VCCA	3	VCCDA	328

CG624	
AX1000 Function	Pin Number
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	AA13
VCCDA	AA15
VCCDA	AA7
VCCDA	AC11
VCCDA	AD11
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

CG624	
AX1000 Function	Pin Number
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3

CG624	
AX1000 Function	Pin Number
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

Revision	Changes	Page
Revision 17 (continued)	The C180 package was removed from product tables and the "Package Pin Assignments" section (PDN 0909).	3-1
	Package names used in the"Axcelerator Family Product Profile" and "Package Pin Assignments" section were revised to match standards given in *Package Mechanical Drawings* (SAR 27395).	i, 3-1
	The "Introduction" section for "User I/Os" was updated as follows: "The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os" (SARs 24181, 24309).	2-11
	Power values in Table 2-4 • Default CLOAD/VCCI were updated to reflect those of SmartPower (SAR 33945).	2-3
	Two parameter names were corrected in Figure 2-10 • Output Buffer Delays. One occurrence of t_{ENLZ} was changed to t_{ENZL} and one occurrence of t_{ENHZ} was changed to t_{ENZH} (SAR 33890).	2-22
	The "Timing Model" section was updated with new timing values. Timing tables in the "I/O Specifications" section were updated to include enable paths. Values in the timing tables in the "Voltage-Referenced I/O Standards" section and "Differential Standards" section were updated. Table 2-63 • R-Cell was updated (SAR 33945).	2-8, 2-26 to 2-53
	Figure 2-11 • Timing Model was replaced (SAR 33043).	2-23
	The timing tables for "RAM" and "FIFO" were updated (SAR 33945).	2-90 to 2-106
	"Data Registers (DRs)" values were modified for IDCODE and USERCODE (SARs 18257, 26406).	2-108
	The package diagram for the "CQ208" package was incorrect and has been replaced with the correct diagram (SARs 23865, 26345).	3-89
Revision 16 (v2.8, Oct. 2009)	The datasheet was updated to include AX2000-CQ2526 information.	N/A
	MIL-STD-883 Class B is no longer supported by Axcelerator FPGAs and as a result was removed.	N/A
	A footnote was added to the "Introduction" in the "Axcelerator Clock Management System" section.	2-75
Revision 15 (v2.7, Nov. 2008)	RoHS-compliant information was added to the "Ordering Information".	ii
	ACTgen was changed to SmartGen because ACTgen is obsolete.	N/A
Revision 14 (v2.6)	In Table 2-4, the units for the P_{LOAD}, P_{10}, and $P_{I/O}$ were updated from mW/MHz to mW/MHz.	2-3
	In the "Pin Descriptions"section, the HCLK and CLK descriptions were updated to include tie-off information.	2-9
	The "Global Resource Distribution" section was updated.	2-70
	The " CG624" table was updated.	3-116
Revision 13 (v2.5)	A note was added to Table 2-2.	2-1
	In the "Package Thermal Characteristics", the temperature was changed from 150°C to 125°C.	2-6

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84